TOSHIBA Bi-CMOS Integrated Circuit Silicon Monolithic

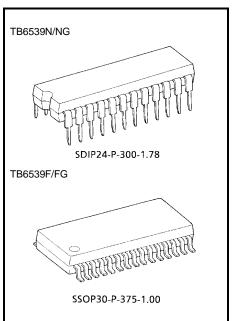
TB6539N/NG, TB6539F/FG

3-PHASE FULL-WAVE SINE-WAVE PWM BRUSHLESS MOTOR CONTROL

Features

- Sine-wave PWM control
- Built-in triangular-wave generator (carrier cycle = f_{osc}/252 (Hz))
- Built-in lead angle control function (0 to 58° in 32 steps)
- Built-in dead time function
- Over-current protection signal input pin
- Built-in regulator (V_{refout} = 5 V (typ.), 30 mA (max))
- Operating supply voltage range: VCC = 10 to 18 V

VM = 4.5 to 18 V



TB6539NG/FG:

The TB6539NG/FG is a Pb-free product. The following conditions apply to solderability: *Solderability

- Use of Sn-37Pb solder bath
 *solder bath temperature = 230°C
 *dipping time = 5 seconds
 *number of times = once
 *use of R-type flux
- Use of Sn-3.0Ag-0.5Cu solder bath *solder bath temperature = 245°C
 *dipping time = 5 seconds
 *number of times = once
 *use of R-type flux

Weight

SDIP24-P-300-1.78 : 1.62 g (typ.) SSOP30-P-375-1.00 : 0.63 g (typ.)

Block Diagram

LA (23/29) Xin (14/17) System clock 6-bit triangular generator wave generator 4/5) V_M X_{out} 15/19 HU 21/26 5-bit AD Phase Comparator 4 bits U 5/6 U Counter HV (20/25 Position detector × Phase 8/9 X Output HW 19/23 Data Comparator Ľ vaveform V Setting Internal reference voltage select ∔ 6/7 V ſ Phase generato dead \sim Phase Ve (22/27 9/10 Y natching Comparator time 111 W Regulator V_{CC} (1/1 Ц 7/8) W Switching 120/180 120°/180 10/12) Z P-GND 3/4 and S-GND 13/16 Charger gate V_{refout} (24/30) Rotating Comparator block PWM (16/20) OS FG Power-on direction rotectior HU reset on/off HV 120°-RES (18/22 HW turn-on ST/SP I_{dc} (2/3 matrix CW/CCW Protection & CW/CCW (17/21 ERR GB reset FG (11/14 REV (12/15

 $\%\,$ The pin numbers shown above are for the TB6539N/NG/TB6539F/FG $\,$

TB6539N/NG/F/FG

2

Pin Description

Pin	Pin No.			
TB6539N /NG	TB6539F /FG	Symbol	Description	Remarks
21	26	HU	Positional signal input pin U	When positional signal is HHH or LLL, gate block
20	25	HV	Positional signal input pin V	protection operates.
19	23	HW	Positional signal input pin W	With built-in pull-up resistor
17	21	CW/CCW	Rotation direction signal input pin	L: Forward H: Reverse
18	22	RES	Reset-signal-input pin	L: Reset (output is non-active) Operation/Halt operation Also used for gate block protection
22	27	Ve	Inputs voltage instruction signal	With built-in pull-down resistor
23	29	LA	Lead angle setting signal input pin	Sets 0 to 58° in 32 steps
16	20	OS	Inputs output logic select signal	L: Active low H: Active high
2	3	I _{dc}	Inputs over-current- protection-signal	Inputs DC link current. Reference voltage: 0.5 V With built-in filter (\simeq 1 μ s)
14	17	X _{in}	Inputs clock signal	With huild in facely active
15	19	X _{out}	Outputs clock signal	With built-in feedback resistor
24	30	V _{refout}	Outputs reference voltage signal	5 V (typ.), 30 mA (max)
11	14	FG	FG signal output pin	Outputs 3PPR of positional signal
12	15	REV	Reverse rotation detection signal	Detects reverse rotation.
5	6	U	Outputs turn-on signal	
6	7	V	Outputs turn-on signal	
7	8	W	Outputs turn-on signal	Select active high or active low using the output logic select pin.
8	9	Х	Outputs turn-on signal	
9	10	Y	Outputs turn-on signal	
10	12	Z	Outputs turn-on signal	
1	1	V _{CC}	Power supply voltage pin	V _{CC} = 10~18 V
4	5	V _M	Apply power supply for output circuit.	$V_{M} = 4.5 \sim 18 V$
3	4	P-GND	Ground for power supply	Ground pin
13	16	S-GND	Ground for signals	Ground pin

Input/Output Equivalent Circuits

Pin Description	Symbol	Input/Output Signal	Input/Output Internal Circuit
Positional signal input pin U Positional signal input pin V Positional signal input pin W	HU HV HW	Digital With Schmitt trigger Hysteresis 300 mV (typ.) L: 0.8 V (max) H: V _{refout} – 1 V (min)	V _{refout} V _{refout}
Forward/reverse switching input pin L: Forward (CW) H: Reverse (CCW)	CW/CCW	Digital With Schmitt trigger Hysteresis 300 mV (typ.) L: 0.8 V (max) H: V _{refout} – 1 V (min)	Vrefout Vrefout C C C C C C C C C C C C C C C C C C C
Reset input L: Stops operation (reset). H: Operates.	RES	Digital With Schmitt trigger Hysteresis 300 mV (typ.) L: 0.8 V (max) H: V _{refout} – 1 V (min)	Vrefout 2 kΩ W Vrefout X Vrefout X Vrefout
Voltage instruction signal input pin Turn on the lower transistor at 0.2 V or less. (X, Y, Z pins: ON duty of 8%)	Ve	Analog Input range 0 to 5.0 V Input voltage of V _{refout} or higher is clipped to V _{refout} .	
Lead angle setting signal input pin 0 V: 0° 5 V: 58° (5-bit AD)	LA	Analog Input range 0 to 5.0 V Input voltage of V _{refout} or higher is clipped to V _{refout} .	

TB6539N/NG/F/FG

Pin Description	Symbol	Input/Output Signal	Input/Output Internal Circuit		
Output logic select signal input pin L: Active low H: Active high	OS	Digital L: 0.8 V (max) H: V _{refout} – 1 V (min)	Vrefout Vrefout Q Q Q Q Vrefout Q Q Q Q Q Q Q Q Q Q Q Q Q Q Q Q Q Q Q		
Over-current protection signal input pin	I _{dc}	Analog Gate block protected at 0.5 V or higher (released at carrier cycle)	V _{CC} $200 k\Omega$ L_{a} L_{a} L_{a} L_{a} Comparator		
Clock signal input pin	X _{in}	Operating range	Vrefout Xin $\xrightarrow{V_{refout}}$ Xout \xrightarrow{T} $\xrightarrow{V_{refout}}$ Xout		
Clock signal output pin	X _{out}	2 to 8 MHz (crystal oscillation)			
Reference voltage signal output pin	Vrefout	5 ± 0.5 V (max 30 mA)	V _{CC} V _{CC}		
Reverse-rotation-detection signal output pin	REV	Digital Open collector output: 20 mA (max)	V _{CC}		

TB6539N/NG/F/FG

Pin Description	Symbol	Input/Output Signal	Input/Output Internal Circuit
FG signal output pin	FG	Digital Open collector output: 20 mA (max)	Vcc
Turn-on signal output pin U Turn-on signal output pin V Turn-on signal output pin W Turn-on signal output pin X Turn-on signal output pin Y Turn-on signal output pin Z	U V W X Y Z	Analog Push-pull output: 20 mA (max) L: 1.3 V (max) H: V _M – 1.3 V (min)	VM VM

Absolute Maximum Ratings (Ta = 25°C)

Characterist	ics	Symbol	Rating	Unit		
Supply voltage	un huudtono		anly voltage		18	V
Supply vollage		VM	18	v		
Input voltage		V _{in (1)}	-0.3~V _{CC} (Note 1)	V		
input voltage		V _{in (2)}	-0.3~5.5 (Note 2)	v		
Turn-on signal output cu	urrent	IOUT	20	mA		
Power dissipation	N/NG Type	PD	1.75 (Note 3)	W		
Power dissipation	F/FG Type	FD	1.50 (Note 4)	vv		
Operating temperature		T _{opr}	-30~115 (Note 5)	°C		
Storage temperature		T _{stg}	-50~150	°C		

Note 1: Vin (1) pin: Ve, LA, REV, FG

Note 2: Vin (2) pin: HU, HV, HW, CW/CCW, RES, OS, Idc

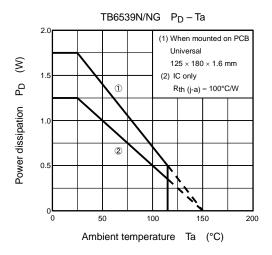
Note 3: When mounted on a PCB (universal $125 \times 180 \times 1.6$ mm)

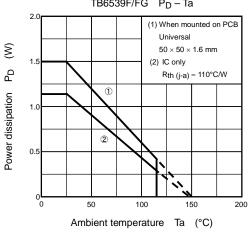
Note 4: When mounted on a PCB (universal $50 \times 50 \times 1.6$ mm)

Note 5: Operating temperature range is determined by the P_D – Ta characteristic.

Operating Conditions (Ta = 25°C)

Characteristics	Symbol	Min	Тур.	Max	Unit	
Supply voltage	V _{CC}	10	15	18	V	
	V _M	4.5	5	18	v	
Crystal oscillation frequency	X _{in}	2	4	8	MHz	





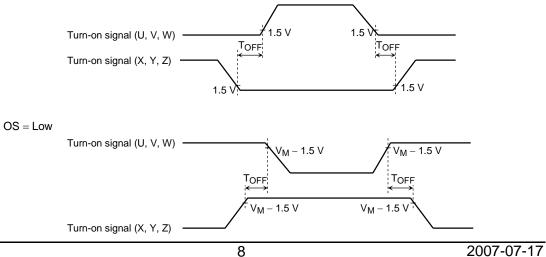
TB6539F/FG P_D – Ta

Electrical Characteristics (Ta = 25° C, V_{CC} = 15 V)

Characteristics	Symbol	Test Circuit	Test Condition	Min	Тур.	Max	Unit	
Supply ourront	Icc		V _{refout} = OPEN	—	20	30	m ^	
Supply current	I _M		$V_{M} = 5 V$	_	8	12	mA	
	I _{in (1)}		V _{in} = 5 V V _e , LA	_	25	40		
Input current	I _{in (2)} -1		V _{in} = 0 V HU, HV, HW	-40	-25			
input current	I _{in (2)} -2		V _{in} = 0 V CW/CCW, OS	-80	-50		μA	
	I _{in (2)} -3		V _{in} = 5 V RES	_	50	80		
Input voltage	V _{in} High	_	HU, HV, HW, CW/CCW, RES, OS	V _{refout} - 1		V _{refout}	v	
	Low					0.8		
Input hysteresis voltage	V _H	_	HU, HV, HW, CW/CCW, RES		0.3	_	V	
	V _{OUT (H)-1}	OUT (H)-1	$I_{OUT} = 20 \text{ mA} \qquad \qquad U, V, W, X, Y, Z$ $V_{M} = 5 \text{ V}$	V _M - 1.3	V _M - 1.0	_		
Output voltage	Vout (L)-1	_	$I_{OUT} = -20 \text{ mA} \qquad U, V, W, X, Y, Z$ $V_M = 5 \text{ V}$	_	1.0	1.3	v	
	V _{REV}		I _{OUT} = -20 mA REV	_	1.0	1.3		
	V _{refout}		I _{OUT} = 30 mA V _{refout}	4.5	5.0	5.5		
	V _{FG}		I _{OUT} = -20 mA FG	_	1.0	1.3		
Output leakage	IL (H)		$V_M = 15 \text{ V}, V_{OUT} = 0 \text{V} \qquad \text{U}, \text{V}, \text{W}, \text{X}, \text{Y}, \text{Z}$	_	0	10	μA	
current	I _{L (L)}		$V_{M} = 15 \text{ V}, \text{ V}_{OUT} = 15 \text{ V} $ U, V, W, X, Y, Z	_	0	10	μΛ	
Output off-time by upper/lower transistor			$V_M = 5 \text{ V}/15 \text{ V}, \text{ I}_{OUT} = \pm 20 \text{ mA}$ $OS = \text{High/Low, } X_{\text{in}} = 4.19 \text{ MHz} \qquad (\text{Note 1})$	3.0	3.8	_	μS	
Over-current detection	V _{dc}		I _{dc}	0.45	0.5	0.55	V	
	T _{LA (0)}		$L_A = 0$ V or Open, Hall IN = 100 Hz	_	0			
Lead angle correction	T _{LA (2.5)}		L _A = 2.5 V, Hall IN = 100 Hz	27.5	32	34.5	0	
	T _{LA (5)}		$L_A = 5 \text{ V}, \text{ Hall IN} = 100 \text{ Hz}$	53.5	59	62.5		
	V _{CC (H)}		Output start operation point	7.5	8.5	9.5		
V _{CC} monitor	V _{CC (L)}	No output operation point		6.5	7.5	8.5	V	
	V _{HYS}			—	1.0			

Note 1:

OS = High



Functional Description

Basic operation

On start-up, the motor is driven by the square-wave turn-on signal based on a positional signal. When the positional signal reaches number of rotations f = 5 Hz or higher, the rotor position is inferred from the positional signal and a modulation wave is generated. The modulation wave and the triangular wave are compared; the sine-wave PWM signal is then generated and the motor is driven.

From start to 5 Hz: When driven by square wave (120° turn-on), $f = f_{osc}/(2^{12} \times 32 \times 6)$ 5 Hz~: When driven by sine-wave PWM (180° turn-on) When $f_{osc} = 4$ MHz, approx. 5 Hz

Function to stabilize bootstrap voltage

- (1) When voltage instruction is input at $V_e \leq 0.2 V$: The lower transistor is turned on at the regular (carrier) cycle. (On duty is approx. 8%.)
- (2) When voltage instruction is input at $V_e > 0.2 V$:

During sine-wave drive, the drive signal is output as it is.

During square-wave drive, the lower transistor is forcibly turned on at the regular (carrier) cycle. (On duty is approx. 8%.)

Note: At startup, to charge the upper transistor gate power supply, turn the lower transistor on for a fixed time with $V_e \leq 0.2 V$.

Dead time function: upper/lower transistor output off-time

When the motor is driven by a sine-wave PWM, dead time is generated digitally in the IC to prevent any short circuit caused by the simultaneous turning on of upper and lower external power devices.

```
Dead time: T_d = 16/f_{osc} (s) When f_{osc} = 4 MHz, approx. T_d = 4 \mu s.
```

 $f_{osc} = reference \ clock \ (crystal \ oscillation)$

Correcting lead angle

The lead angle can be corrected in the turn-on signal range from 0 to 58° in relation to the induced voltage.

Analog input from LA pin (0 to 5 V divided by 32): 0 V = 0°

 $5 \text{ V} = 58^{\circ}$ (when more than 5 V is input, 58°)

Setting carrier frequency

This feature sets the triangular wave cycle (carrier cycle) necessary for generating the PWM signal. (The triangular wave is used for forcibly turning on the lower transistor when the motor is driven by square wave.)

Carrier cycle = $f_{osc}/252$ (Hz)

fosc = reference clock (crystal oscillation)

Switching the output of turn-on signal

This function switches the output of the turn-on signal between high and low.

Pin OS:

High = active high Low = active low

Outputting reverse rotation detection signal

The direction of motor rotation is detected for every electrical angle of 360°. (The output is high immediately after reset.)

The REV terminal increases to a 180° turn-on mode at the time of High-Z.

CW/CCW Pin	Actual Motor Rotating Direction	REV Pin	
Low (CW)	CW (forward)	High-Z	
	CCW (reverse)	Low	
High (CCW)	CW (forward)	Low	
	CCW (reverse)	High-Z	

<u>TOSHIBA</u>

Protecting input pin

1. Over-current protection (Pin Idc)

When the DC-link-current exceeds the internal reference voltage, gate block protection is performed. Over-current protection is released for each carrier frequency.

- Reference voltage = 0.5 V (typ.)
- 2. Gate block protection (Pin RES)

When the input signal level is Low, the output is turned off; when the signal is High, the output is restarted.

Abnormalities are detected externally, and the signal is input to the pin RES.

RES Pin	OS Pin	Output Turn-on Signal (U, V, W, X, Y, Z)		
Low	Low	High		
LOW	High	Low		

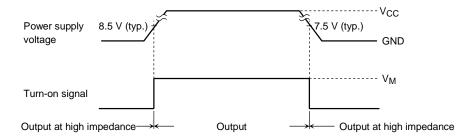
(When RES = Low, bootstrap capacitor charging stops.)

- 3. Internal protection
 - Positional signal abnormality protection

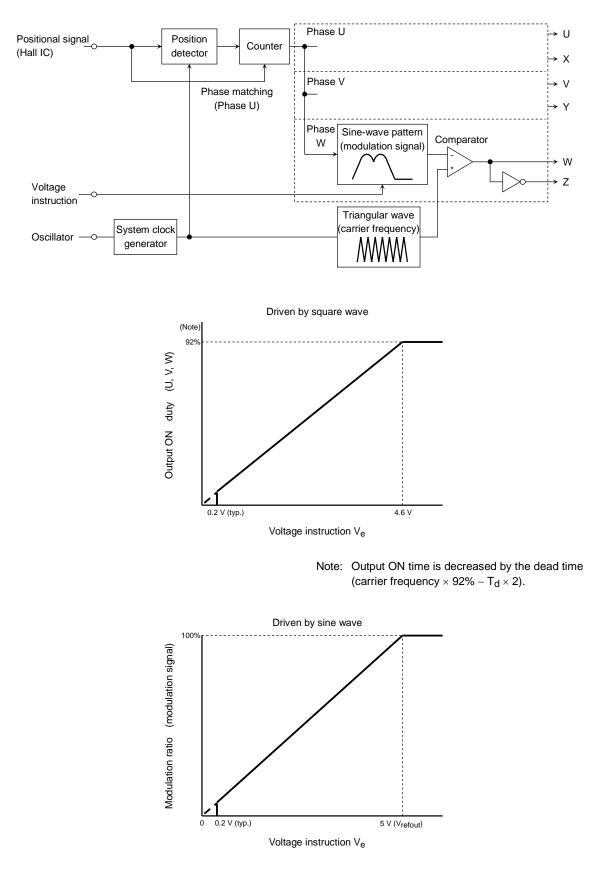
When the positional signal is HHH or LLL, the output is turned off; otherwise, the output is restarted.

• Low power supply voltage protection (V_{CC} monitor)

Outside the operating voltage range, the turn on signal output is kept at high impedance to prevent damage caused by short-circuiting of power components when the power supply is turned on or off.



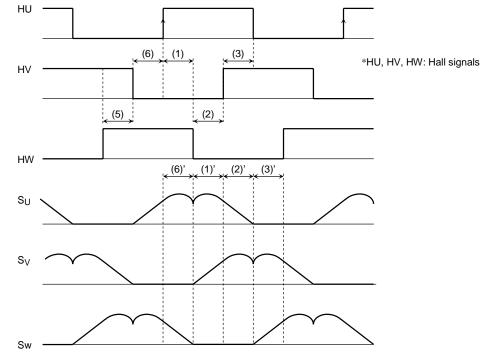
Operation Flow



The modulation waveform is generated using Hall signals. The modulation waveform is then compared with the triangular wave and a sine-wave PWM signal is generated.

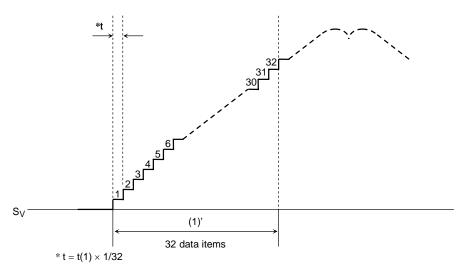
The time (electrical angle: 60°) from the rising (or falling) edges of the three Hall signals to the next rising (or rising) edges is counted. The counted time is used as the data for the next 60° phase of the modulation waveform.

There are 32 items of data for the 60° phase of the modulation waveform. The time width of one data item is 1/32 of the time width of the 60° phase of the previous modulation waveform. The modulation waveform moves forward by this width.



In the above diagram, the modulation waveform (1)" data moves forward by the 1/32 time width of the time (1) from HU: \uparrow to HW: \downarrow . Similarly, data (2)' moves forward by the 1/32 time width of the time (2) from HW: \downarrow to HV: \uparrow .

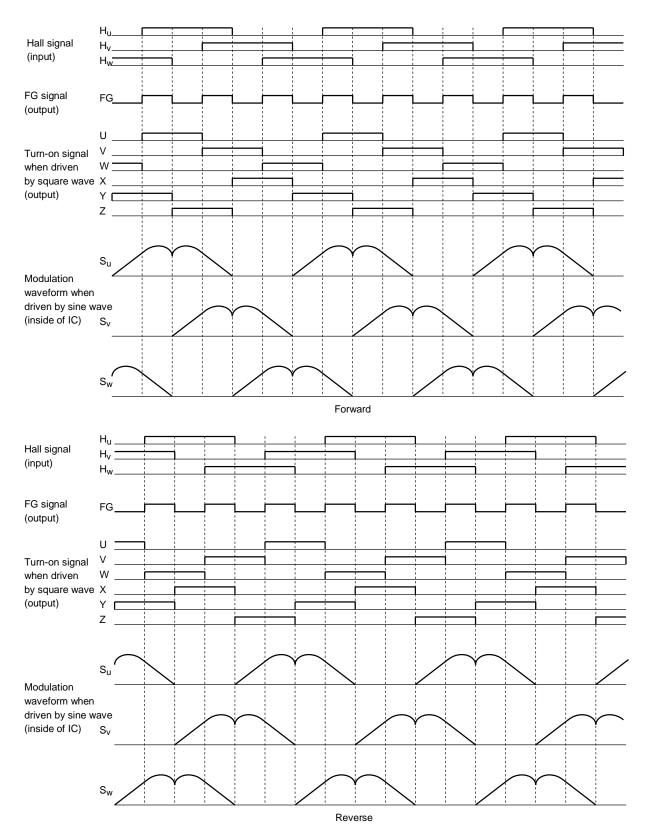
If the next edge does not occur after the 32 data items end, the next 32 data items move forward by the same time width until the next edge occurs.



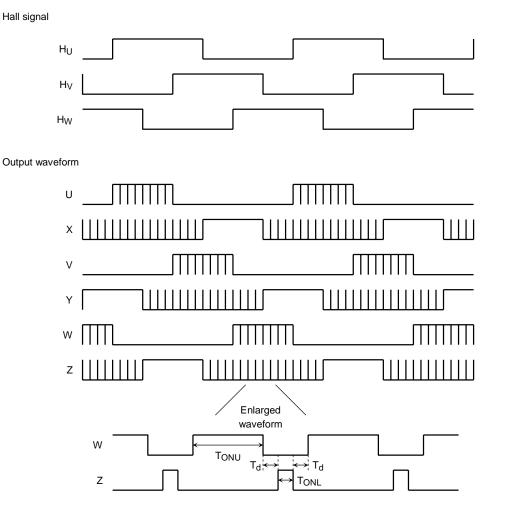
The phases are matched between every rising edge of the HU signal and the modulation waveform. The modulation waveform is reset in synchronization with the rising edge of the HU signal at every electrical angle of 360°. Thus, when the Hall signal rising edge is off-position or during acceleration or deceleration, the modulation waveform is non-consecutive at every reset.

<u>TOSHIBA</u>

Timing Charts



Operating Waveform When Driven by Square Wave (CW/CCW = Low, OS = High)



To stabilize the bootstrap voltage, the lower outputs (X, Y, and Z) are always turned on at the carrier cycle even during off time. At that time, the upper outputs (U, V, and W) are assigned dead time and turned off at the timing when the lower outputs are turned on. (T_d varies with input V_e .)

Carrier cycle = $f_{osc}/252$ (Hz) Dead time: Td

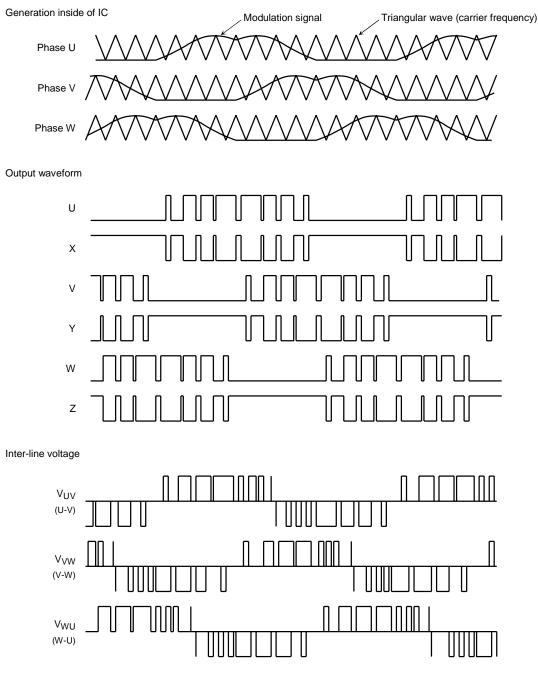
Dead time: $T_d = 16/f_{osc}$ (s) (when $V_e = 4.6$ V or more)

 $TONL = carrier cycle \times 8\%$ (s) (uniform regardless of Ve input)

When the motor is driven by a square wave, acceleration or deceleration is determined by voltage V_e . The motor accelerates or decelerates according to the On duty of T_{ONU} . (See the diagram for output On duty on page 11.)

Note: The motor is driven by a square wave if REV = Low, i.e., if the Hall signals at start-up are 5 Hz (fosc = 4 MHz) or lower and the motor is rotating in the reverse direction to that of the TB6551F/FG setting.

Operating Waveform When Driven by Sine-Wave PWM (CW/CCW = Low, OS = High)

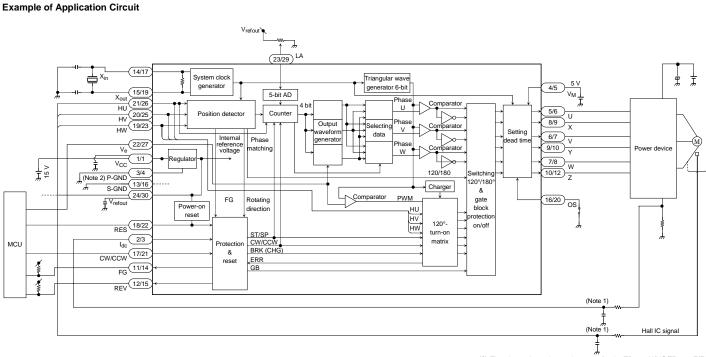


When driven by a sine wave, the motor is accelerated or decelerated according to the On duty of T_{ONU} when the amplitude of the modulation symbol changes by voltage V_e (see the diagram of output On duty on page 11).

Triangular wave frequency = carrier frequency = $f_{OSC}/252$ (Hz)

Note: The motor is driven by a sine wave if REV = High-Z, i.e., if the Hall signals at start-up are 5 Hz (fosc = 4 MHz) or higher and the motor is rotating in the same direction as that of the TB6551F/FG setting.

TB6539N/NG/F/FG



* The pin numbers shown above are for the TB6539N/NG/TB6539F/FG

Note 1: Connect as required to the ground to prevent IC malfunction due to noise.

Note 2: Connect P-GND to signal ground on the application circuit.

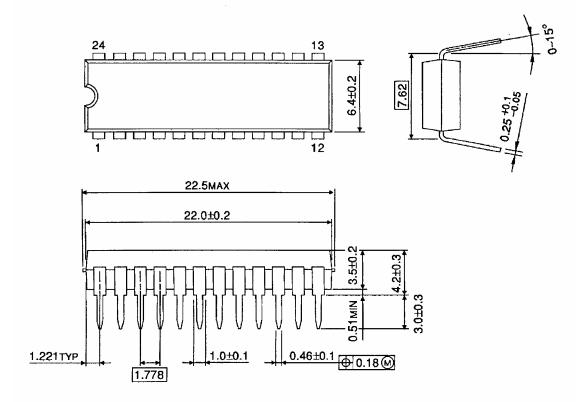
Note 3: Utmost care is necessary in the design of the output, V_{CC}, V_M, and GND lines since the IC may be destroyed by short-circuiting between outputs, air contamination faults, or faults due to improper grounding, or by short-circuiting between contiguous pins.

16

Package Dimensions

SDIP24-P-300-1.78

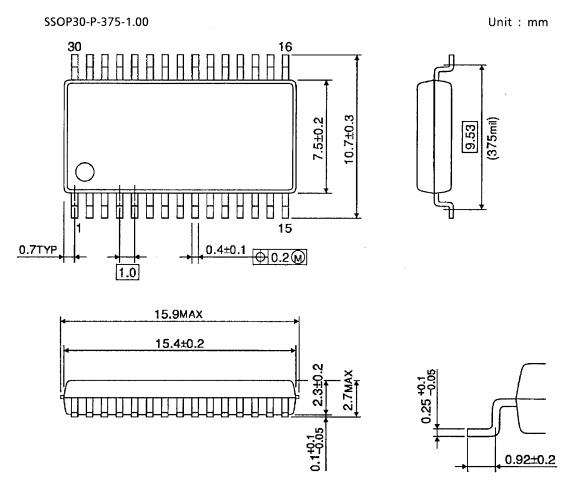
Unit : mm



Weight: 1.62 g (typ.)

<u>TOSHIBA</u>

Package Dimensions



Weight: 0.63 g (typ.)

Notes on Contents

1. Block Diagrams

Some of the functional blocks, circuits, or constants in the block diagram may be omitted or simplified for explanatory purposes.

2. Equivalent Circuits

The equivalent circuit diagrams may be simplified or some parts of them may be omitted for explanatory purposes.

3. Timing Charts

Timing charts may be simplified for explanatory purposes.

4. Application Circuits

The application circuits shown in this document are provided for reference purposes only. Thorough evaluation is required, especially at the mass production design stage.

Toshiba does not grant any license to any industrial property rights by providing these examples of application circuits.

5. Test Circuits

Components in the test circuits are used only to obtain and confirm the device characteristics. These components and circuits are not guaranteed to prevent malfunction or failure from occurring in the application equipment.

IC Usage Considerations Notes on handling of ICs

- The absolute maximum ratings of a semiconductor device are a set of ratings that must not be exceeded, even for a moment. Do not exceed any of these ratings.
 Exceeding the rating(s) may cause the device breakdown, damage or deterioration, and may result injury by explosion or combustion.
- [2] Do not insert devices in the wrong orientation or incorrectly.

Make sure that the positive and negative terminals of power supplies are connected properly. Otherwise, the current or power consumption may exceed the absolute maximum rating, and exceeding the rating(s) may cause the device breakdown, damage or deterioration, and may result injury by explosion or combustion.

In addition, do not use any device that is applied the current with inserting in the wrong orientation or incorrectly even just one time.

Points to remember on handling of ICs

(1) Heat Radiation Design

In using an IC with large current flow such as power amp, regulator or driver, please design the device so that heat is appropriately radiated, not to exceed the specified junction temperature (T_J) at any time and condition. These ICs generate heat even during normal use. An inadequate IC heat radiation design can lead to decrease in IC life, deterioration of IC characteristics or IC breakdown. In addition, please design the device taking into considerate the effect of IC heat radiation with peripheral components.

RESTRICTIONS ON PRODUCT USE

070122EBA_R6

- The information contained herein is subject to change without notice. 021023_D
- TOSHIBA is continually working to improve the quality and reliability of its products. Nevertheless, semiconductor devices in general can malfunction or fail due to their inherent electrical sensitivity and vulnerability to physical stress. It is the responsibility of the buyer, when utilizing TOSHIBA products, to comply with the standards of safety in making a safe design for the entire system, and to avoid situations in which a malfunction or failure of such TOSHIBA products could cause loss of human life, bodily injury or damage to property.
 In developing your designs, please ensure that TOSHIBA products are used within specified operating ranges as set forth in the most recent TOSHIBA products specifications. Also, please keep in mind the precautions and conditions set forth in the "Handling Guide for Semiconductor Devices," or "TOSHIBA Semiconductor Reliability Handbook" etc. 021023_A
- The TOSHIBA products listed in this document are intended for usage in general electronics applications (computer, personal equipment, office equipment, measuring equipment, industrial robotics, domestic appliances, etc.). These TOSHIBA products are neither intended nor warranted for usage in equipment that requires extraordinarily high quality and/or reliability or a malfunction or failure of which may cause loss of human life or bodily injury ("Unintended Usage"). Unintended Usage include atomic energy control instruments, airplane or spaceship instruments, transportation instruments, traffic signal instruments, combustion control instruments, medical instruments, all types of safety devices, etc. Unintended Usage of TOSHIBA products listed in this document shall be made at the customer's own risk. 021023_B
- The products described in this document shall not be used or embedded to any downstream products of which manufacture, use and/or sale are prohibited under any applicable laws and regulations. 060106_Q
- The information contained herein is presented only as a guide for the applications of our products. No responsibility is assumed by TOSHIBA for any infringements of patents or other rights of the third parties which may result from its use. No license is granted by implication or otherwise under any patents or other rights of TOSHIBA or the third parties. 070122_C
- Please use this product in compliance with all applicable laws and regulations that regulate the inclusion or use of controlled substances.
 Toshiba assumes no liability for damage or losses occurring as a result of noncompliance with applicable laws and regulations. 060819_AF
- The products described in this document are subject to foreign exchange and foreign trade control laws. 060925_E